



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Group Art Unit: 2814
Examiner: Phat X. Cao

In re PATENT APPLICATION of:

Applicant(s): Nobuhisa KUMAMOTO et al.

Serial No.: 10/767,439

Filing date: January 30, 2004

For: PROCESS OF PRODUCING
SEMICONDUCTOR CHIP WITH SURFACE
INTERCONNECTION AT BUMP (as amended)

Atty. ref.: AI 318 D1

AMENDMENT

March 19, 2007

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

This is responsive to the Office Action of October 18, 2006, the period for reply to which is being extended to expire March 18, 2007 (a Sunday, and thus on the following Monday, March 19, 2007), by a Petition filed concurrently herewith.

A fee of \$ 450 is also being submitted concurrently. Should this remittance be accidentally missing, however, or should any additional fees be needed, the Director may charge such fees to our Deposit Account number 18-0002.

Please amend above-identified application as specified on the following pages, and then reconsider the application in view of the Remarks that are presented thereafter.